

Amendments to the Claims:

The following listing of claims will replace all prior versions, and listings, of claims in the application:

1. (Previously Presented) An electronic device comprising:
a substrate on which an interconnect pattern is formed;
a chip component having a first surface on which an electrode is formed and a second surface opposite to the first surface, the chip component being mounted in such a manner that the second surface faces the substrate, the chip component having a passivation film formed on the first surface;
an insulating section formed of a resin and provided adjacent to the chip component; and
an interconnect which is formed to extend from above the electrode, directly on the insulating section, on the passivation film, and above the interconnect pattern, the insulating section being formed so that part of the insulating section under the interconnect does not overlay the first surface.
2. (Original) The electronic device as defined by claim 1,
wherein a side surface of the chip component is inclined to descend in an outward direction from the first surface.
3. (Original) The electronic device as defined by claim 1,
wherein the chip component has a step in an edge portion of the chip component.
- 4-5. (Canceled).
6. (Original) The electronic device as defined by claim 1,
wherein the insulating section has a portion higher than the first surface.
7. (Original) The electronic device as defined by claim 1, further comprising:
a connection layer that connects the chip component with the substrate.

8. (Original) The electronic device as defined by claim 7,
wherein the connection layer is formed of the same material as the insulating section.
9. (Original) The electronic device as defined by claim 7,
wherein the connection layer is formed of a material different from a material of the insulating section.
10. (Previously Presented) An electronic device comprising:
a substrate on which an interconnect pattern is formed;
a chip component having a first surface on which an electrode is formed and a second surface opposite to the first surface, the chip component being mounted in such a manner that the second surface faces the substrate, the chip component having a passivation film formed on the first surface;
an insulating section provided adjacent to the chip component and having an inclined surface descending in an outward direction from the chip component; and
an interconnect which is formed to extend from above the electrode, directly on the insulating section, on the passivation film, and above the interconnect pattern, the insulating section being formed so that part of the insulating section under the interconnect does not overlay the first surface.
11. (Original) The electronic device as defined by claim 10,
wherein the inclined surface is a depressed surface.
12. (Original) The electronic device as defined by claim 10,
wherein the inclined surface is a projected surface.
- 13-14. (Canceled).
15. (Original) The electronic device as defined by claim 10,
wherein the insulating section has a portion higher than the first surface.
16. (Original) The electronic device as defined by claim 10, further comprising:

a connection layer that connects the chip component with the substrate.

17. (Original) The electronic device as defined by claim 16,
wherein the connection layer is formed of the same material as the insulating
section.
18. (Original) The electronic device as defined by claim 16,
wherein the connection layer is formed of a material different from a material
of the insulating section.
- 19-30. (Canceled).
31. (Original) A circuit board on which an electronic device as defined in claim 1
is mounted.
32. (Original) A circuit board on which an electronic device as defined in claim
10 is mounted.
33. (Original) An electronic instrument having an electronic device as defined in
claim 1.
34. (Original) An electronic instrument having an electronic device as defined in
claim 10.